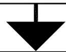

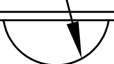

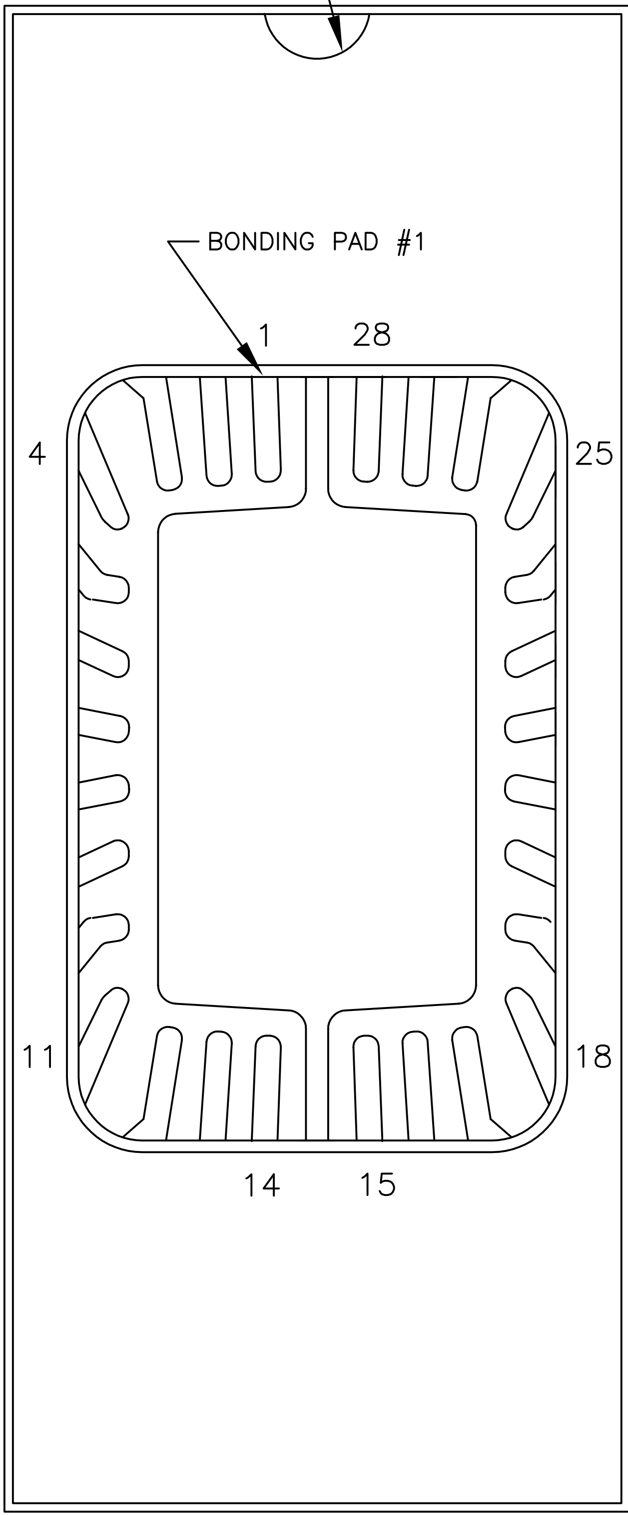

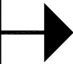

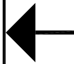

DEVICE TYPE:				
CUSTOMER:		DIE SIZE:		
WIRE TYPE/ SIZE:		NO. OF WIRES:		
THIRD ANGLE PROJECTION	REVISIONS			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES DO NOT SCALE DRAWING	ECN NO.	DATE	DESCRIPTION	APPROVED
	10518	11/3/05	PRODUCTION RELEASE	D.BENANDO
DRAWN BY W. GRIFFITTS	DATE 11/2/05	PACKAGE SIZE: 0.710" x 0.295"		
APP BY P. FLASKERUD	DATE 11/2/05	DIE PAD SIZE: 0.230" x 0.160"		

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Open-Pak™ Technologies
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PHONE: (408) 400-9002 FAX: (408) 400-9006

28 Lead 300 mils SOIC Open–Pak Bonding Diagram

SIZE	PART NO.		REV
A	SOIC300–28–OP–01		2
SCALE 18X	CAD FILE SOIC300–28–OP–01–B–R2.DWG	SHEET 1 OF 1